



PCN Number: MC110816

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**Product/Process Change Notification (PCN)**

**Customer:** Newark

**Date:** 11/08/2016

**Customer Part # and/or Lot# affected:** A6260KLJTR-T and A6260SLJTR-T

**Originator:** Mark Caggiano

**Phone:** 603-626-2538

**Duration of Change:**

Permanent  Temporary (explain)

**Summary description of change:** Part Change:  Process Change:  Other:

1. Allegro currently manufactures the A6260KLJTR-T and A6260SLJTR-T on the 6" wafer fab ABCD4 technology line at Polar Semiconductor LLC (PSL), Bloomington, MN, USA. The 6" ABCD4 wafer fab line will be closing. Allegro will change manufacturing to the 8" ABCD4 technology wafer fab line at Polar Semiconductor LLC (PSL), Bloomington, MN, USA
2. The A6260KLJTR-T and A6260SLJTR-T will change the final test location from Allegro MicroSystems, LLC Worcester, MA USA to Allegro MicroSystems (Thailand) Co., Ltd. (AMTC).

**What is the part or process changing from (provide details)?**

1. Allegro currently manufactures the A6260KLJTR-T and A6260SLJTR-T on the 6" wafer fab ABCD4 technology line at Polar Semiconductor LLC (PSL), Bloomington, MN, USA, The 6" ABCD4 wafer fab line will be closing.
2. The A6260KLJTR-T and A6260SLJTR-T final test location is Allegro MicroSystems, LLC, Worcester, MA USA.

**What is the part or process changing to (describe the anticipated impact of this change on form, fit and/or function)?**

1. The A6260KLJTR-T and A6260SLJTR-T will change manufacturing to the 8 inch wafer fab ABCD4 technology line at Polar Semiconductor LLC (PSL), Bloomington, MN, USA..
2. The A6260KLJTR-T and A6260SLJTR-T will change final test locations to Allegro MicroSystems (Thailand) Co., Ltd. (AMTC).

Allegro will be expanding its manufacturing capabilities with the addition of a new, wholly-owned integrated circuit test facility located in Saraburi, Thailand. The same make and model test equipment will be utilized and test site transfer buy off data will be on file for each device before production begins.



**Note:** Validation of equivalence within a specific application is at the discretion of the Customer

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**Is a PPAP update required?**

Yes

No

**Is reliability testing required?**

(If Yes, refer to attached plan)

Yes

No (explain)



**Reliability Qualification Results**

Device: 6260 (9326)

Assy Lot #: 1548731UAAA

Number of Leads: 8

Fab Location: PSL

Package: LJ (eSOIC)

Assembly Location: Unisem

Lead Finish: 100% Sn

Tracking Number: 3316

**Reason for Qualification: 6260 (9326) - [6" to 8" Fab Transfer] - Automotive, High Brightness LED, Current Regulator**

Reliability Qualification Results						
6260 (9326) - STR#3316						Requirements
Stress Test	Abv.	Test #	Test Method	Test Conditions	S.S.	Results
Preconditioning	PC	A1	JESD22-A113 / J-STD-020	85°C/60% RH, 168 hrs, Peak Reflow=260°C; MSL3, (HAST, AC, TC)	231	0 Rejects
HAST	HAST	A2	JESD22-A110	Ta=130°C, 85% RH, 2 ATM, 0, 96 hrs	77	0 Rejects
Autoclave	AC	A3	JESD22-A102	Ta=121°C, 100% RH, 15 PSIG, 0, 96 hrs	77	0 Rejects
Temperature Cycle	TC	A4	JESD22-A104	Ta = -65°C to +175°C, 0, 500, 1000 Cycles	77	0 Rejects
Wire Bond Pull	WBP	C2	Mil-Std-883 Method 2011	Temp conditions and sample size are defined in the test method. (after TC)		0 Rejects; Cpk>1.67
High Temperature Operating Life	HTOL	B1	JESD22-A108	Ta=125°C, 0, 1000 hrs	77	0 Rejects
Early Life Failure Rate	ELFR	B2	AEC-Q100-008 / JESD22-A108	Ta=125°C, 0, 48 hrs	800	0 Rejects
Electrostatic Discharge Human Body Model	HBM	E2	AEC-Q100-002 / JS-001-2014	Test Conditions, Sampling Size are defined in the Test Method		Classification H2, HBM = 2.0kV
Electrostatic Discharge Charged Device Model	CDM	E3	AEC-Q100-011	Test Conditions, Sampling Size are defined in the Test Method		Classification C6, > 1kV
Latch-Up	LU	E4	JESD78	Test Conditions, Sampling Size are defined in the Test Method		Class II, Level A
Electrical Distributions	ED	E5	AEC Q100-009	Tri-Temp Electrical Distributions - 30 pcs. (1 Lot)		0 Rejects; Cpk>1.67

This device qualification is considered to be passing all environmental stress evaluations per the *Allegro MicroSystems, LLC* 900019 specification and AEC-Q100.

Approved by:

*Bob Demers*

Bob Demers  
Product Safety and Reliability  
Allegro MicroSystems, LLC

*Allegro MicroSystems, LLC*

*Proprietary*

**Expected completion date for internal qualification: Complete**

**Expected PPAP availability date: N/A**

**Target implementation date: May 2017**



**Estimated date of first shipment: June 2017**

**Expected sample availability date: Available Upon Request**

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**Customer Approval Required:** Yes  **Date Required:**  
No  **Notification Only**

**Please note:** It is our intention to inform our customer of changes as early as possible. Under Allegro's procedure for product/process change notification, Allegro strives, based on its technical judgment, to provide notification of significant changes that may affect form, fit or function. However, as Allegro cannot ensure evaluation of product/process changes for each and every application; the customer retains responsibility to validate the impact of a change on its application suitability. If samples are needed for validation of a change, requests may be made via the contact information provided herein. Please contact your Account Manager or local Sales contact for any questions. We would kindly request your consideration so we can meet our target date for implementation. Unless both parties agree to extend the implementation date, this change will be implemented as scheduled.

Customer comments/Conditions of Acceptance:

Approved by: \_\_\_\_\_ Date: \_\_\_\_\_ Title: \_\_\_\_\_  
cc: Allegro Sales/Marketing/Quality